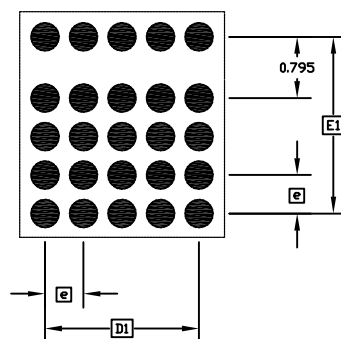


RECOMMENDED LAND PATTERN



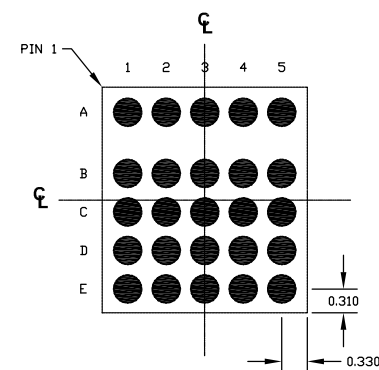
NOTES:

1. REFERENCE PKG. OUTLINE: 21-0924
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: ± 0.02 MM.
4. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
5. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—

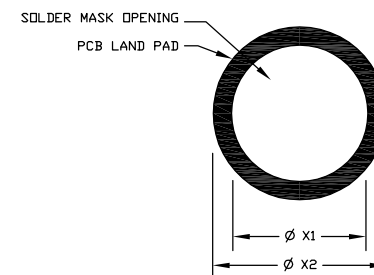
This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maximintegrated.com/support> for further questions.

PACKAGE OVERLAY



| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|-----------|-----|--------|------------|-----|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| D1 | | 2.000 BSC | | | .07874 BSC | |
| E1 | | 2.295 BSC | | | .09035 BSC | |
| e | | 0.50 BSC | | | .01969 BSC | |
| N | | 25 BALLS | | | 25 BALLS | |

PAD DETAIL INFORMATION



| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|-------|-------|--------|--------|--------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| X1 | 0.230 | 0.280 | 0.330 | .00906 | .01102 | .01299 |
| X2 | 0.360 | — | — | .01417 | — | — |



TITLE:
PACKAGE LAND PATTERN,
[C252C2+1] WLCSP

APPROVAL

DOCUMENT CONTROL NO.
90-0553

REV. A

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